

BCR3PM-12L

Triac

Low Power Use

REJ03G0301-0100

Rev.1.00

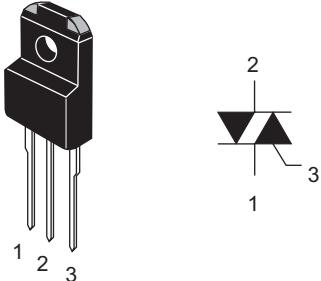
Aug.20.2004

Features

- $I_{T(RMS)}$: 3 A
- V_{DRM} : 600 V
- $I_{FGTI}, I_{RGTI}, I_{RGTI\text{III}}$: 20 mA (10 mA)^{Note5}
- Viso : 2000 V
- Insulated Type
- Planar Passivation Type
- UL Recognized : Yellow Card No. E223904
File No. E80271

Outline

TO-220F



1. T_1 Terminal
2. T_2 Terminal
3. Gate Terminal

Applications

Contactless AC switch, light dimmer, electric blanket, control of household equipment such as electric fan, solenoid driver, small motor control, and other general purpose control applications

Maximum Ratings

Parameter	Symbol	Voltage class		Unit
		12		
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	600		V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	720		V

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_{T\text{ (RMS)}}$	3.0	A	Commercial frequency, sine full wave 360° conduction, $T_c = 107^\circ\text{C}$
Surge on-state current	$I_{T\text{SM}}$	30	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	3.7	A^2s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	$P_{G\text{M}}$	3	W	
Average gate power dissipation	$P_{G\text{ (AV)}}$	0.3	W	
Peak gate voltage	$V_{G\text{M}}$	6	V	
Peak gate current	$I_{G\text{M}}$	0.5	A	
Junction temperature	T_j	-40 to +125	$^\circ\text{C}$	
Storage temperature	T_{stg}	-40 to +125	$^\circ\text{C}$	
Mass	—	2.0	g	Typical value
Isolation voltage	V_{iso}	2000	V	$T_a = 25^\circ\text{C}$, AC 1 minute, $T_1 \cdot T_2 \cdot G$ terminal to case

Notes: 1. Gate open.

Electrical Characteristics

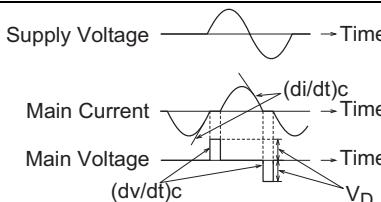
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Repetitive peak off-state current	$I_{D\text{RM}}$	—	—	2.0	mA	$T_j = 125^\circ\text{C}$, $V_{D\text{RM}}$ applied
On-state voltage	$V_{T\text{M}}$	—	—	1.5	V	$T_c = 25^\circ\text{C}$, $I_{T\text{M}} = 4.5$ A, Instantaneous measurement
Gate trigger voltage ^{Note2}	I	$V_{FGT\text{I}}$	—	1.5	V	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	$V_{RG\text{T}\text{I}}$	—	1.5	V	
	III	$V_{RG\text{T}\text{III}}$	—	1.5	V	
Gate trigger current ^{Note2}	I	$I_{FGT\text{I}}$	—	20 ^{Note5}	mA	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	$I_{RG\text{T}\text{I}}$	—	20 ^{Note5}	mA	
	III	$I_{RG\text{T}\text{III}}$	—	20 ^{Note5}	mA	
Gate non-trigger voltage	V_{GD}	0.2	—	—	V	$T_j = 125^\circ\text{C}$, $V_D = 1/2 V_{D\text{RM}}$
Thermal resistance	$R_{\text{th (j-c)}}$	—	—	4.5	$^\circ\text{C/W}$	Junction to case ^{Note3}
Critical-rate of rise of off-state commutating voltage ^{Note4}	$(dv/dt)c$	5	—	—	V/ μ s	$T_j = 125^\circ\text{C}$

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

3. The contact thermal resistance $R_{\text{th (c-f)}}$ in case of greasing is 0.5°C/W .

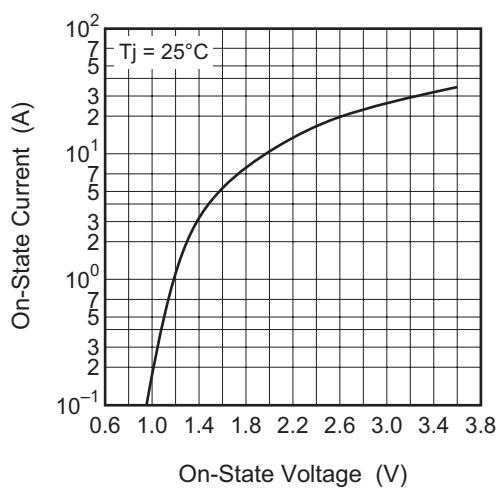
4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

5. High sensitivity ($I_{GT} \leq 10$ mA) is also available. (I_{GT} item: 1)

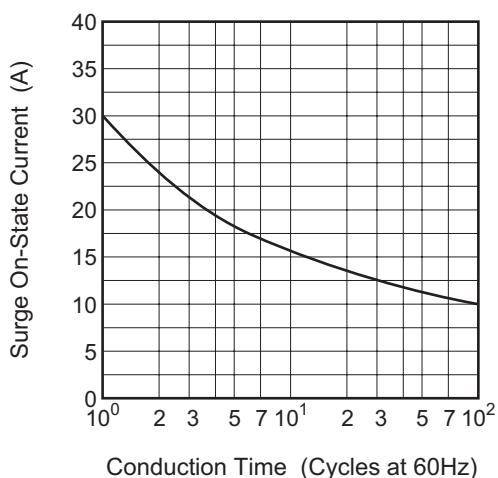
Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)c = -1.5$ A/ms 3. Peak off-state voltage $V_D = 400$ V	

Performance Curves

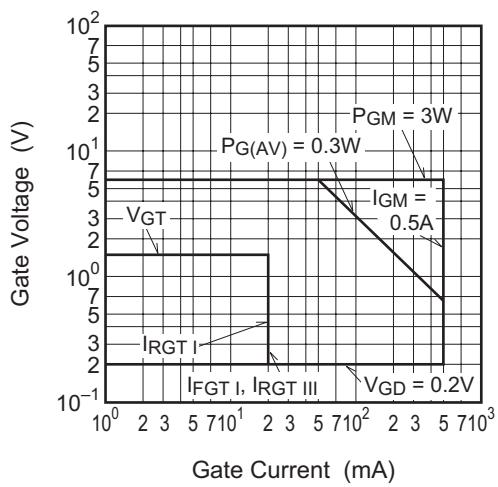
Maximum On-State Characteristics



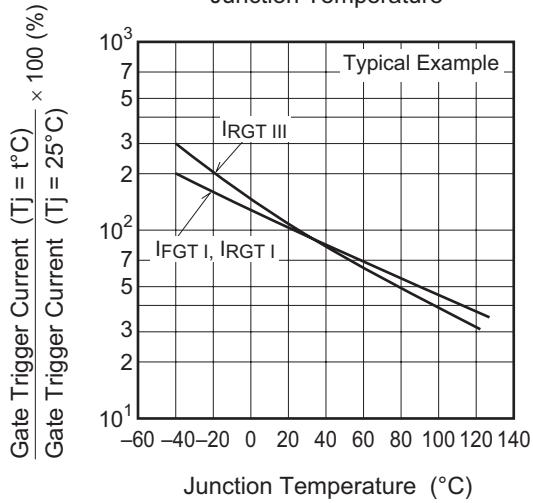
Rated Surge On-State Current



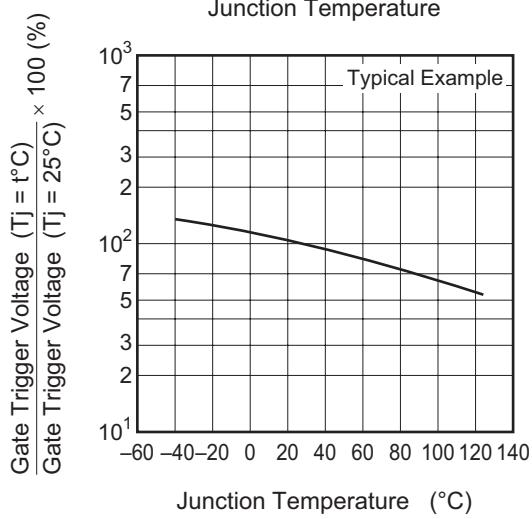
Gate Characteristics (I, II and III)



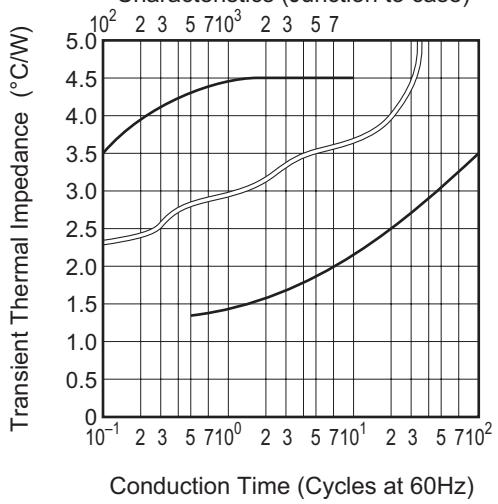
Gate Trigger Current vs. Junction Temperature

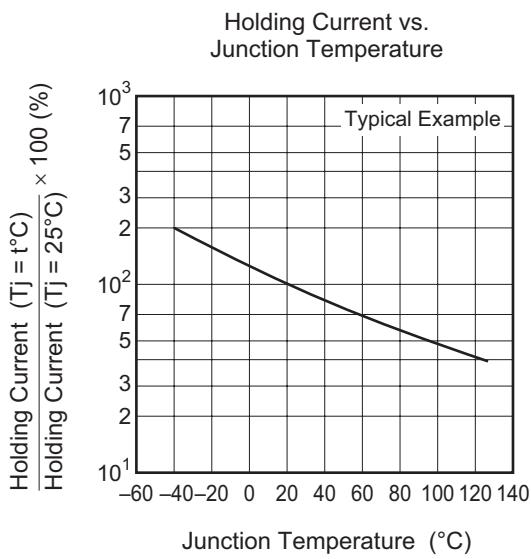
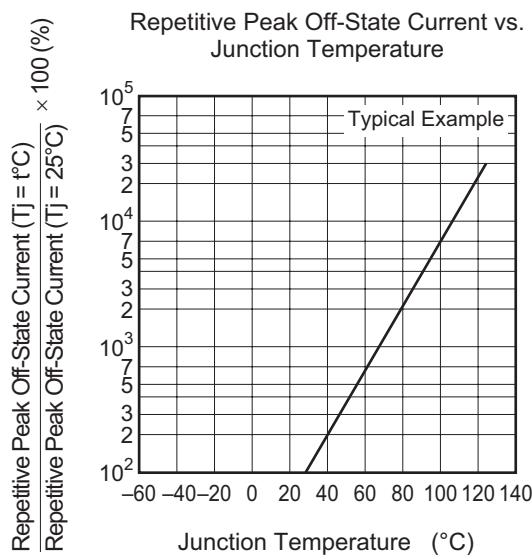
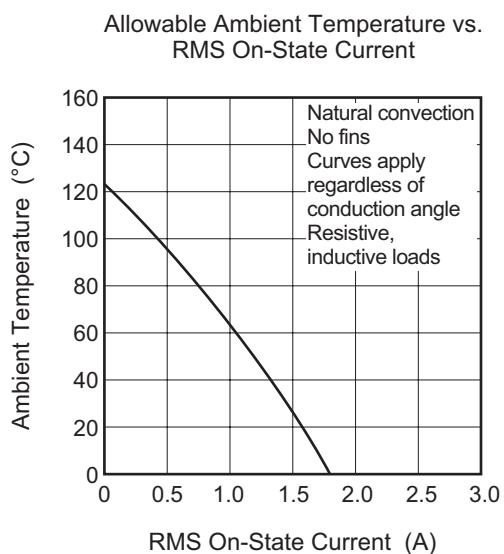
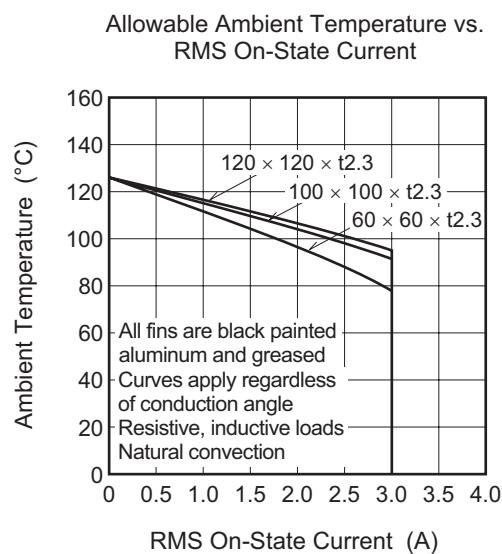
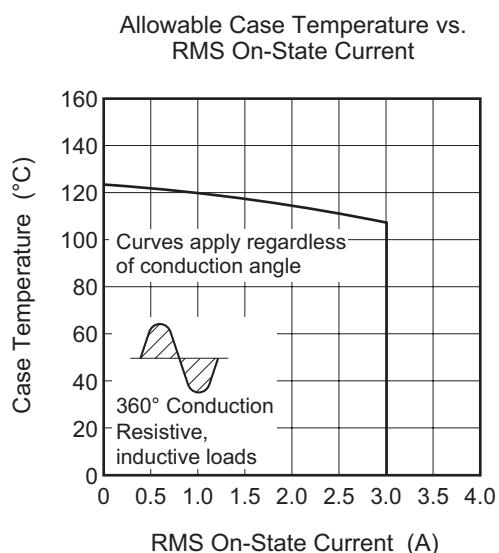
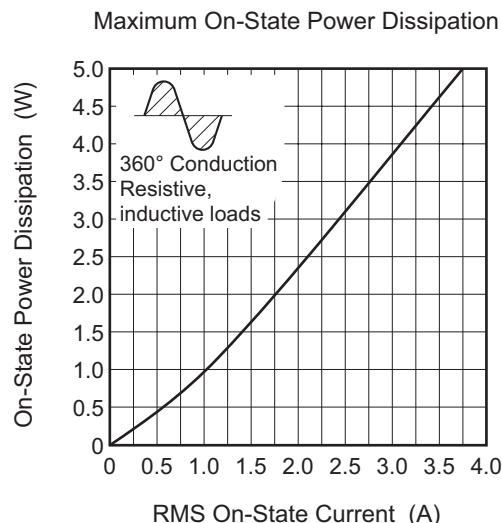


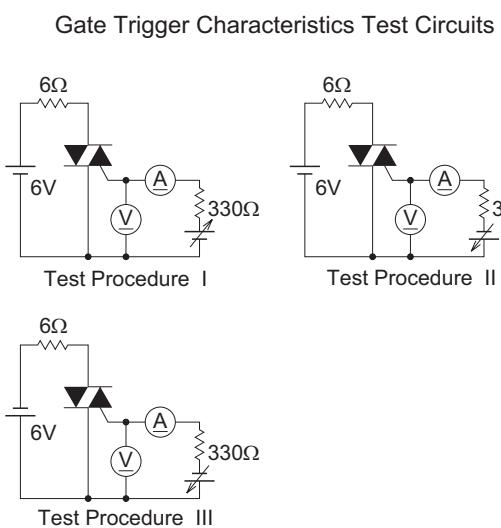
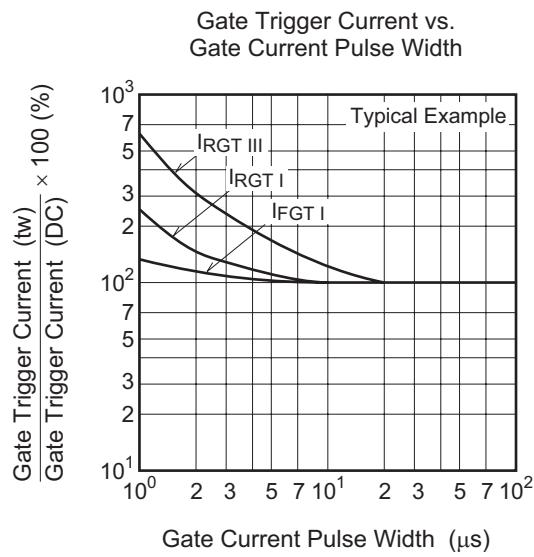
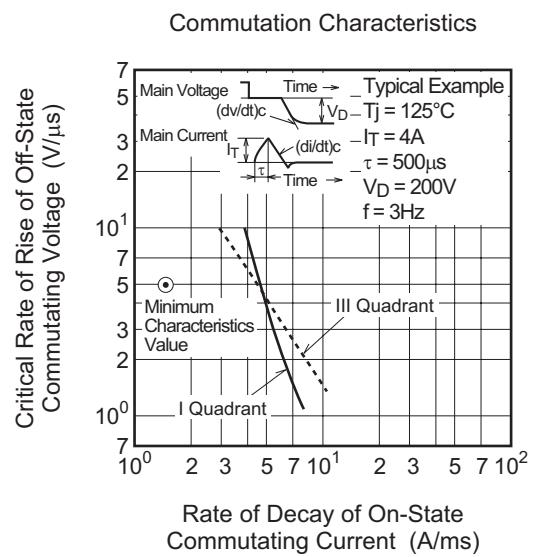
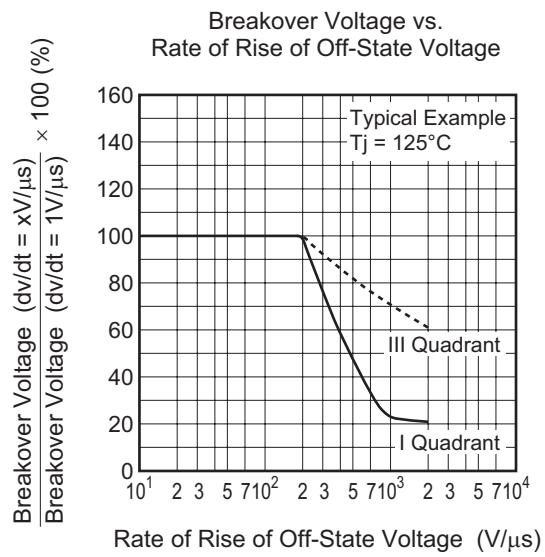
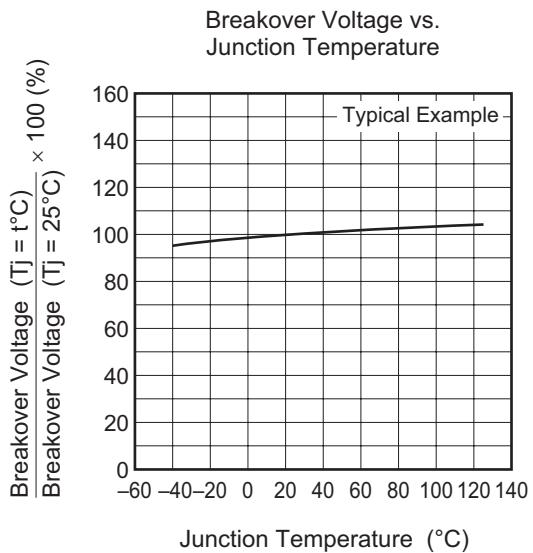
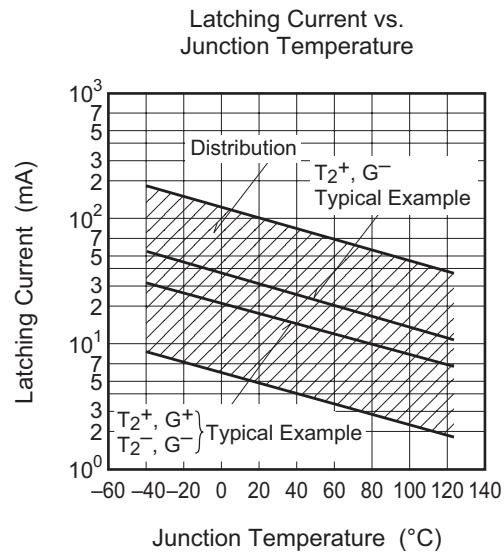
Gate Trigger Voltage vs. Junction Temperature



Maximum Transient Thermal Impedance Characteristics (Junction to case)

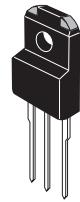
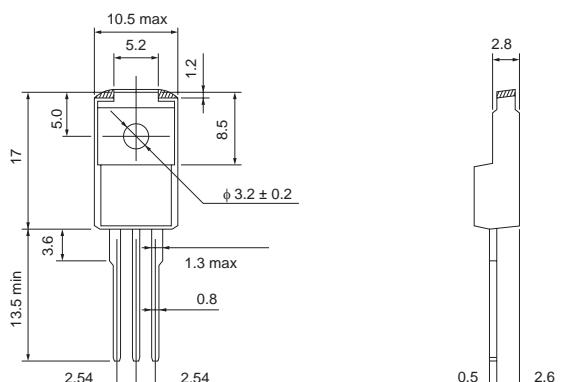
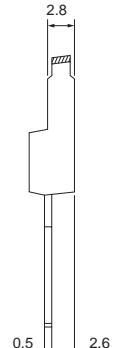


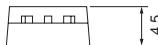




Package Dimensions

TO-220F			
EIAJ Package Code	JEDEC Code	Mass (g) (reference value)	Lead Material
Conforms	—	2.0	Cu alloy



Symbol	Dimension in Millimeters		
	Min	Typ	Max
A			
A ₁			
A ₂			
b			
D			
E			
e			
x			
y			
y ₁			
ZD			
ZE			

Note 1) The dimensional figures indicate representative values unless otherwise the tolerance is specified.

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name +A	BCR3PM-12LA
Lead form	Plastic Magazine (Tube)	50	Type name +A – Lead forming code	BCR3PM-12LA-A8

Note : Please confirm the specification about the shipping in detail.



BCR3PM-12L

Triac

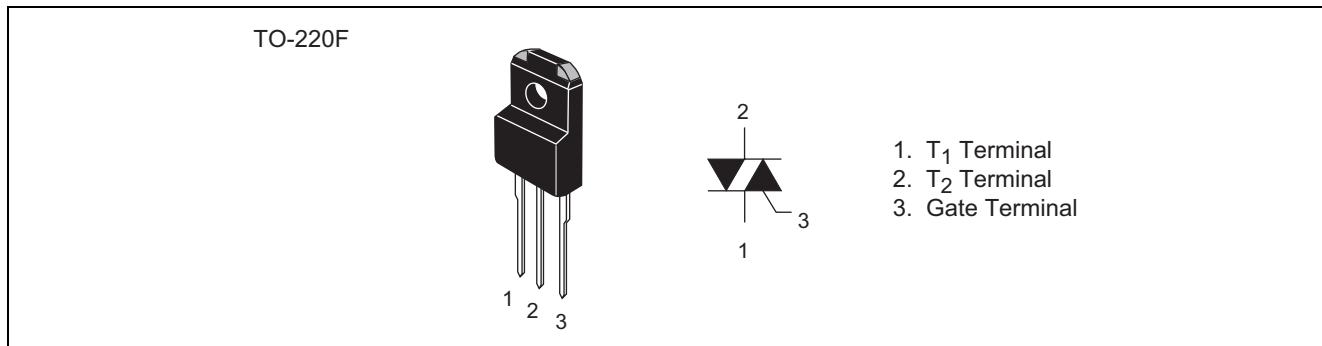
Low Power Use

(The product guaranteed maximum junction temperature of 150°C)

Features

- $I_{T\text{ (RMS)}}$: 3 A
- V_{DRM} : 600 V
- $I_{\text{FGTI}}, I_{\text{RGTI}}, I_{\text{RGTI}_{\text{III}}}$: 20 mA (10 mA)^{Note5}
- Viso : 2000 V
- Insulated Type
- Planar Passivation Type

Outline



Applications

Contactless AC switch, light dimmer, electric blanket, control of household equipment such as electric fan, solenoid driver, small motor control, and other general purpose control applications

Warning

1. Refer to the recommended circuit values around the triac before using.
2. Be sure to exchange the specification before using. Otherwise, general triacs with the maximum junction temperature of 125°C will be supplied.

Maximum Ratings

Parameter	Symbol	Voltage class		Unit
		12	12	
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	600	600	V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	720	720	V

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	I_{TRMS}	3.0	A	Commercial frequency, sine full wave 360° conduction, $T_c = 132^\circ\text{C}$
Surge on-state current	I_{TSM}	30	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	3.7	A^2s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P_{GM}	3	W	
Average gate power dissipation	$P_{\text{G(AV)}}$	0.3	W	
Peak gate voltage	V_{GM}	6	V	
Peak gate current	I_{GM}	0.5	A	
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$	
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$	
Mass	—	2.0	g	Typical value
Isolation voltage	V_{iso}	2000	V	$T_a = 25^\circ\text{C}$, AC 1 minute, $T_1 \cdot T_2 \cdot G$ terminal to case

Notes: 1. Gate open.

Electrical Characteristics

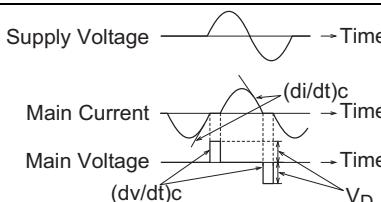
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Repetitive peak off-state current	I_{DRM}	—	—	2.0	mA	$T_j = 150^\circ\text{C}$, V_{DRM} applied
On-state voltage	V_{TM}	—	—	1.5	V	$T_c = 25^\circ\text{C}$, $I_{\text{TM}} = 4.5$ A, Instantaneous measurement
Gate trigger voltage ^{Note2}	I	V_{FGTI}	—	1.5	V	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	V_{RGTI}	—	1.5	V	
	III	V_{RGTH}	—	1.5	V	
Gate trigger current ^{Note2}	I	I_{FGTI}	—	20^{Note5}	mA	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	I_{RGTI}	—	20^{Note5}	mA	
	III	I_{RGTH}	—	20^{Note5}	mA	
Gate non-trigger voltage	V_{GD}	0.2/0.1	—	—	V	$T_j = 125^\circ\text{C}/150^\circ\text{C}$, $V_D = 1/2 V_{\text{DRM}}$
Thermal resistance	$R_{\text{th(j-c)}}$	—	—	4.5	$^\circ\text{C/W}$	Junction to case ^{Note3}
Critical-rate of rise of off-state commutating voltage ^{Note4}	$(dv/dt)_c$	5/1	—	—	V/ μ s	$T_j = 125^\circ\text{C}/150^\circ\text{C}$

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

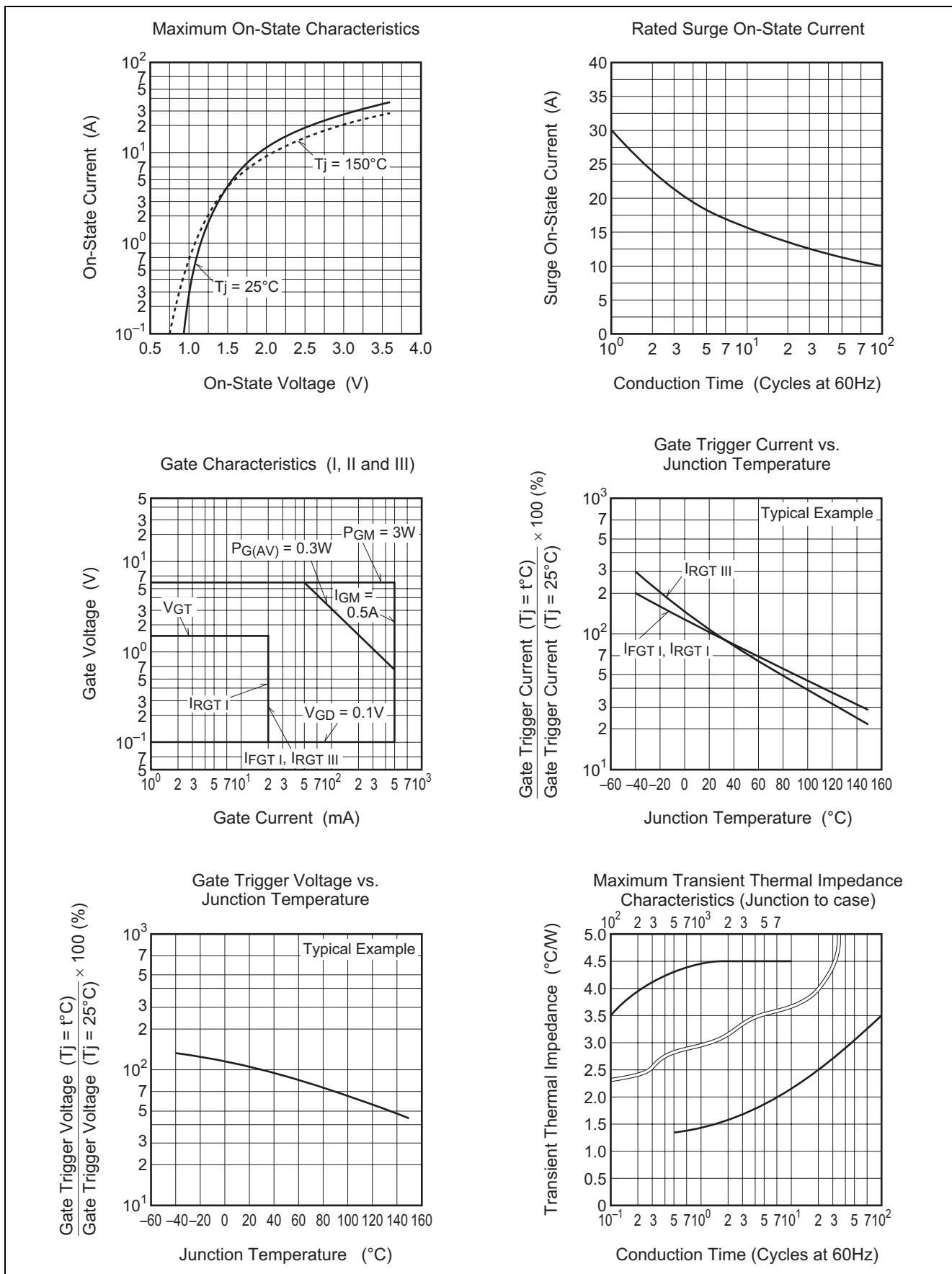
3. The contact thermal resistance $R_{\text{th(c-f)}}$ in case of greasing is 0.5°C/W .

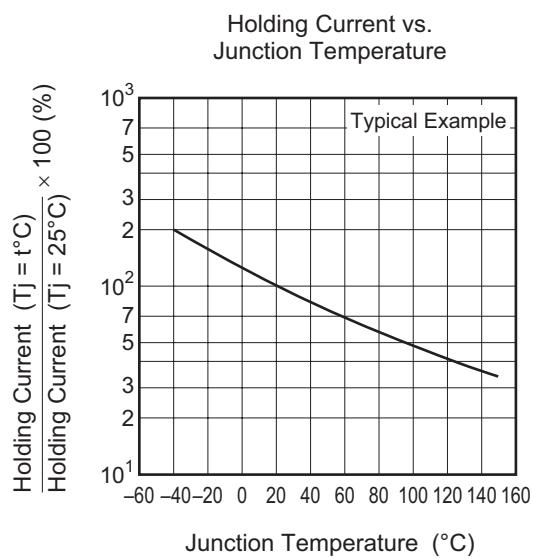
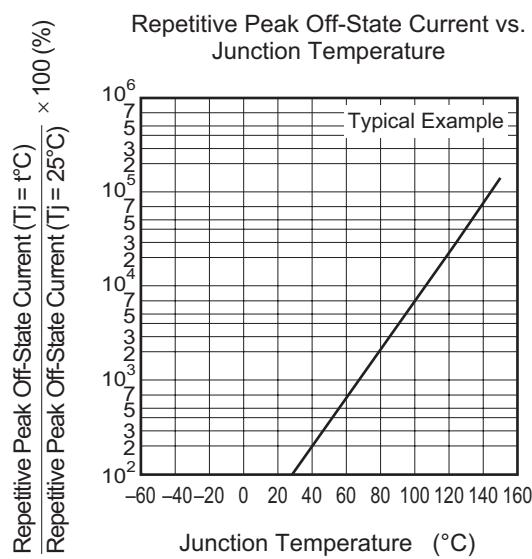
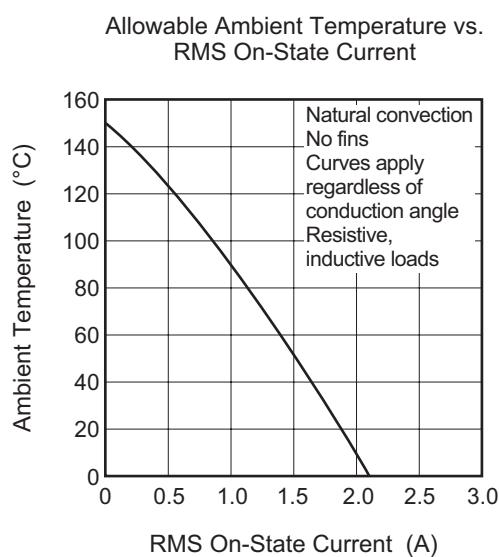
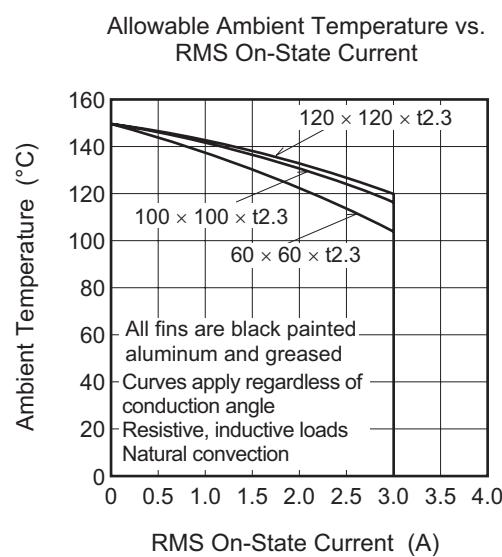
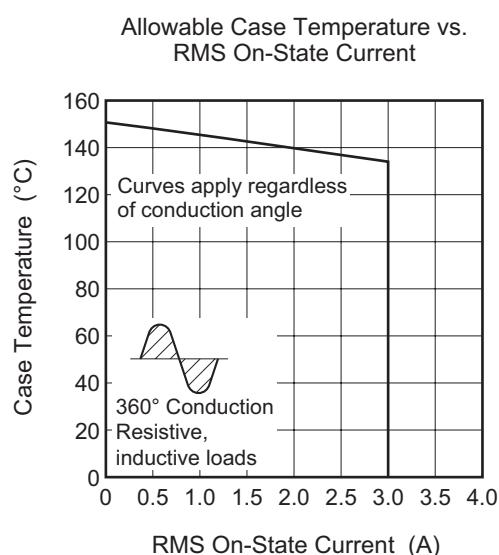
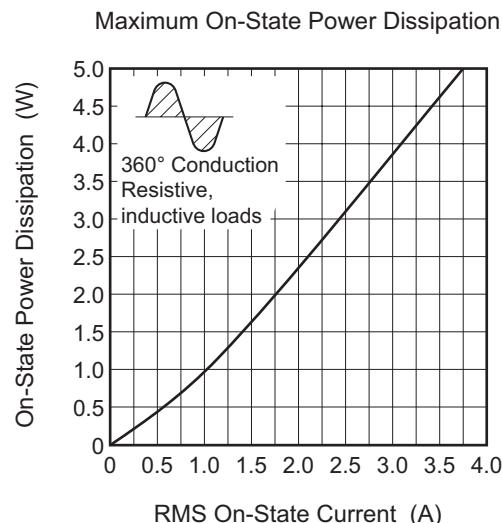
4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

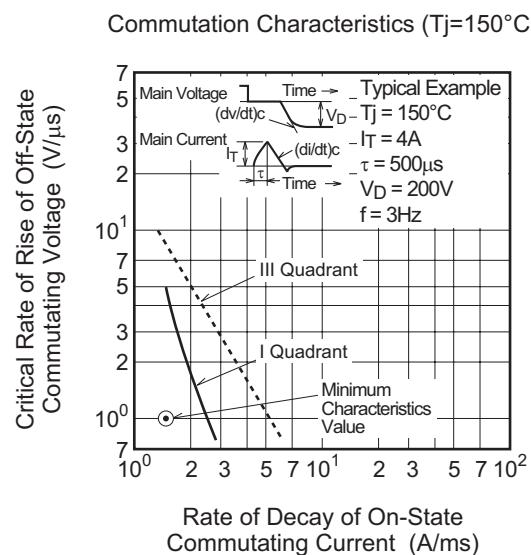
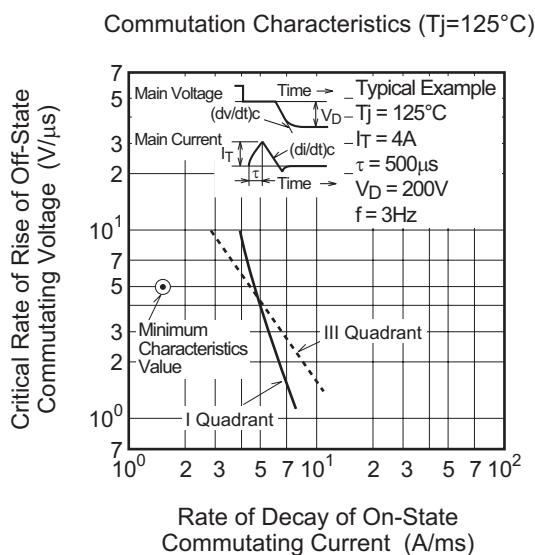
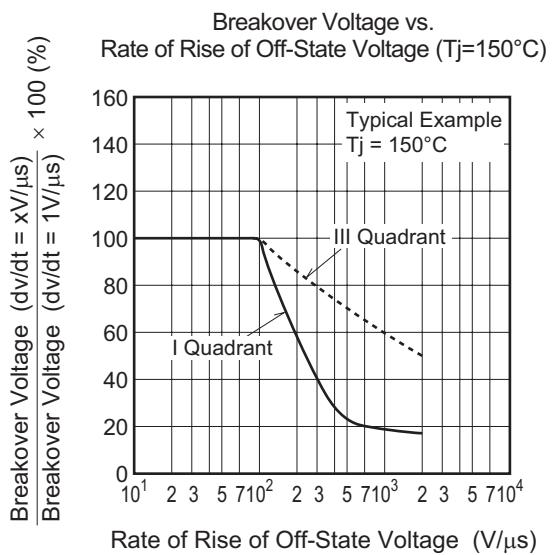
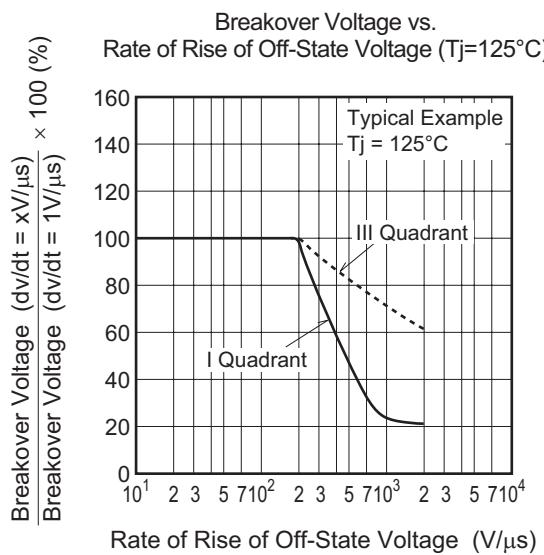
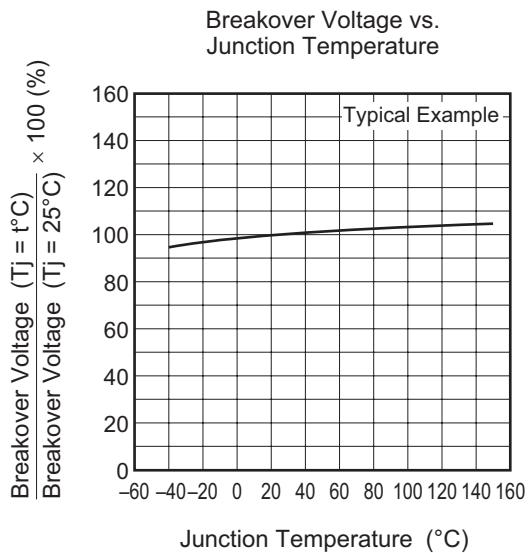
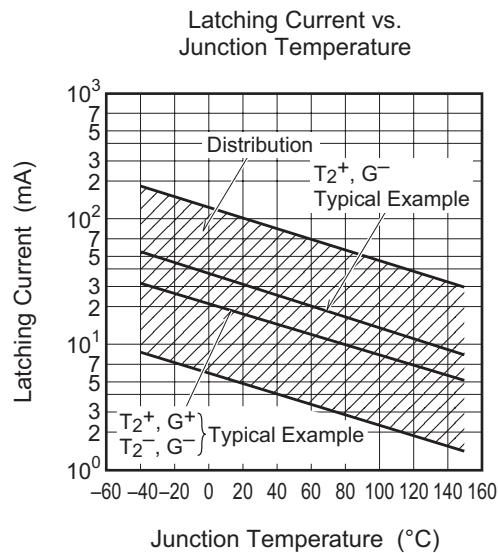
5. High sensitivity ($I_{\text{GT}} \leq 10$ mA) is also available. (I_{GT} item: 1)

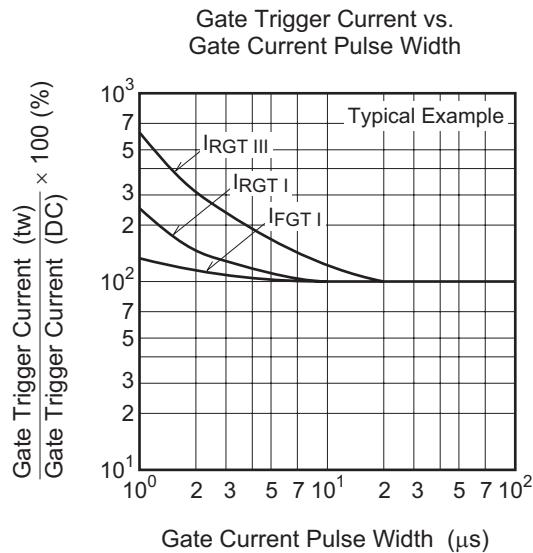
Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}/150^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = -1.5$ A/ms 3. Peak off-state voltage $V_D = 400$ V	

Performance Curves

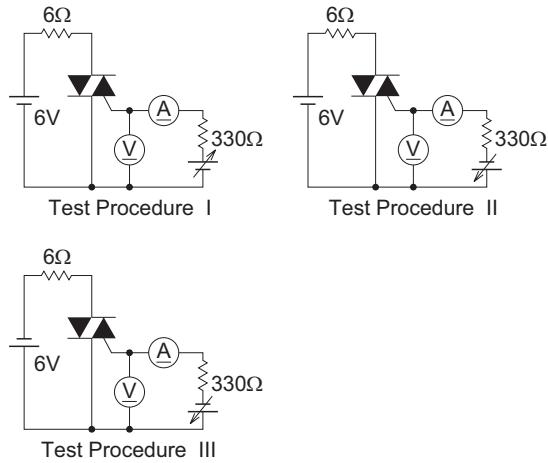




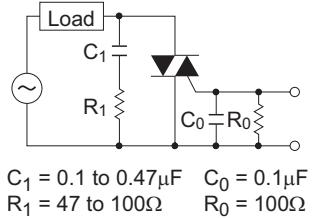




Gate Trigger Characteristics Test Circuits

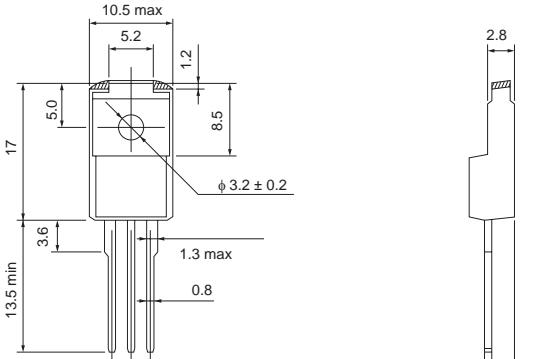
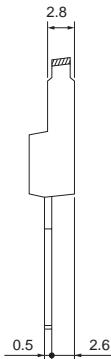
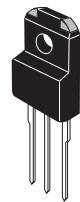


Recommended Circuit Values Around The Triac



Package Dimensions

TO-220F				
EIAJ Package Code	JEDEC Code	Mass (g) (reference value)	Lead Material	
Conforms	—	2.0	Cu alloy	



Symbol	Dimension in Millimeters		
	Min	Typ	Max
A			
A ₁			
A ₂			
b			
D			
E			
e			
x			
y			
y ₁			
ZD			
ZE			

Note 1) The dimensional figures indicate representative values unless otherwise the tolerance is specified.

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name +B	BCR3PM-12LB
Lead form	Plastic Magazine (Tube)	50	Type name +B – Lead forming code	BCR3PM-12LB-A8

Note : Please confirm the specification about the shipping in detail.

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